CRMEGH1509B

N-Channel 150V, 9.7mΩ Typ. Power MOSFET

Description

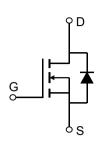
Features

• 150V, 85A

 $R_{DS(ON)}$ Typ = 9.7m Ω @ V_{GS} = 10V

Advanced Split Gate Trench Technology

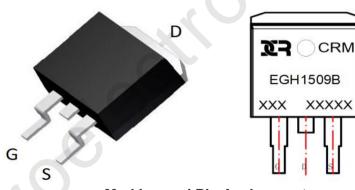
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMEGH1509B	CRMEGH1509B	TO-263-3L	TAPING	13"	800	4800

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		150	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Ocation on Desire Comment	T _C = 25°C	85	Α
I _D	Continuous Drain Current	T _C = 100°C	51	А
I _{DM}	Pulsed Drain Current (1)		340	А
E _{AS}	Single Pulsed Avalanche Energy (2)		306	mJ
P_{D}	Power Dissipation	T _C = 25°C	176	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.71	°C/W
T_J,T_STG	Junction & Storage Temperature Range		-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 150V, V _{GS} = 0V	-	-	1.0	μΑ
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics					
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.4	3.3	3.6	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10V, I_D = 30A$	-	9.7	12.6	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-	2309	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 75V,$ f = 1MHz	-	314	-	pF
C_{rss}	Reverse Transfer Capacitance	1 - 1101112	. - \	14	-	pF
Q_g	Total Gate Charge		-	26	-	nC
Q_gs	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 75V, I_{D} = 20A$)-	9	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} - 73V, I _D - 20A	-	3	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime		-	11	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 75V$	-	9	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	I_D = 20A, R_{GEN} = 10 Ω	-	16	-	ns
t_{f}	Turn-Off Fall Time		-	8	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	85	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	340	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	1 004 177 10047	-	80	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 20A$, di/dt = 100A/us	-	160	_	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =50V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =35A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.

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Test Circuit

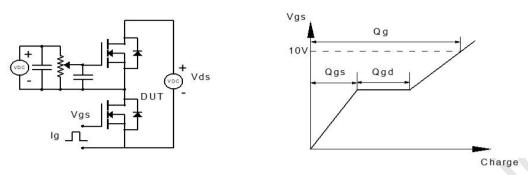


Figure 1: Gate Charge Test Circuit & Waveform

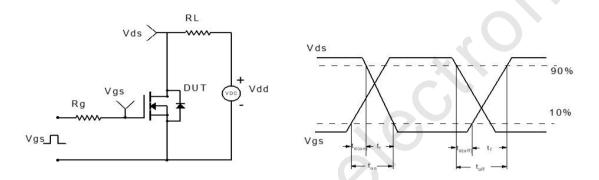


Figure 2: Resistive Switching Test Circuit & Waveform

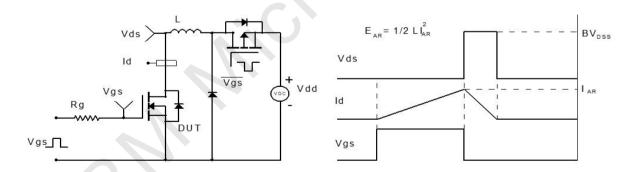


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

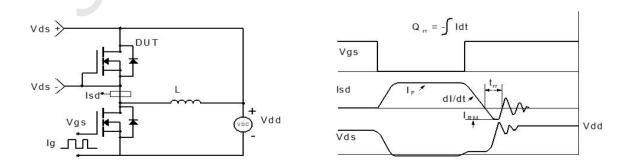
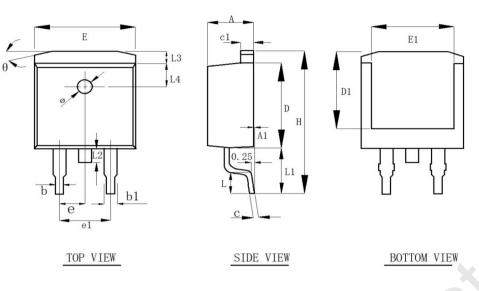


Figure 4: Diode Recovery Test Circuit & Waveform

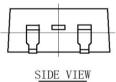
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Package Mechanical Data(TO-263-3L)



		N DIMENSIONS OF MEASURE=mr	n)
SYMBOL	MIN	NOM	MAX
A	4. 30	4. 50	4.70
A1	0.00	NA	0.25
b	0.70	0.80	0. 90
b1	1.20	1.30	1.40
С	0.40	0.47	0.55
c1	1. 25	1.30	1. 35
D	9. 00	9. 10	9. 20
D1	8. 00	8. 10	8, 20
Н	14. 90	15. 20	15. 50
Е	9. 80	10.00	10. 20
E1	7. 85	8.00	8. 15
e1	4. 93	5. 08	5. 23
L	2.00	2. 20	2.45
L1	4.60	4.80	5. 00
L2	1.30	1.50	1.70
L3	1.15	1. 25	1.35
L4	2.40	2.50	2.60
Ø	1.5 REF		
е	2. 54 BSC		
θ	13° TYP		



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